Second Source Supplier Qualification for Substrate Assembly for SSIT Products

XCN17002 (v1.0) April 3, 2017 Product Change Notice

Overview

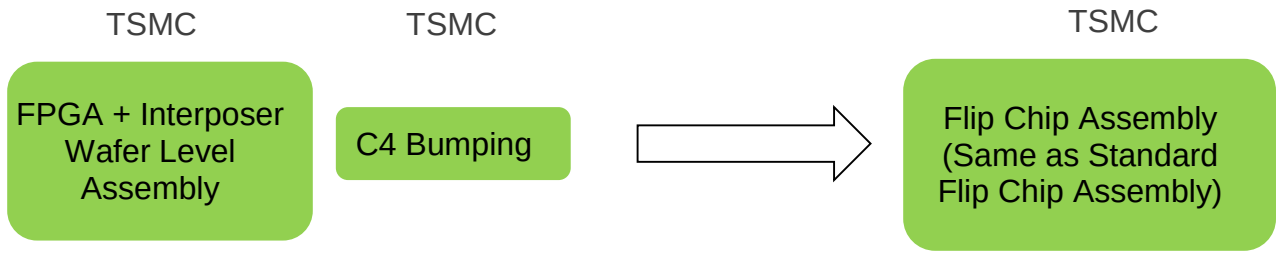
The purpose of this notification is to announce second source supplier qualification for substrate level assembly for SSIT (Stacked Silicon Interconnect Technology) products. There is no change in form, fit, function or reliability.

Description

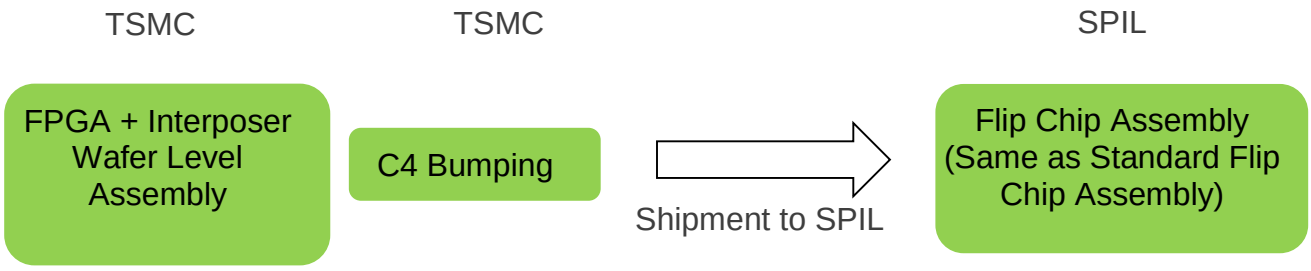
Xilinx qualified SPIL (Siliconware Precision Industries) as a second source supplier for substrate level assembly of stacked die wafers assembled at TSMC. SPIL has been Xilinx's qualified primary flip chip assembly supplier for over 16 years.

In this process flow, TSMC will complete the active die assembly on an interposer and will ship the stacked wafer to SPIL after C4 bumping. SPIL will assemble the stacked die wafer onto substrate similar to a standard flip chip assembly. There is no change in any material sets and the same packaging materials will be used for both process flows. This change is to ensure SSIT product supply continuity.

Current Process



Second Source Process



Products Affected

This change affects all speed, package, and temperature variations of "XC" commercial (C) and industrial (I) products reflected in Table 1 and Table 2. Any associated specification control document (SCD) versions of the standard part numbers are also affected.

Table 1: **Virtex®-7 FPGA Products Affected**

Device	Package-Pin
XC7VH870T	FLG1932
XC7VH580T	FLG1155
	FLG1931
XC7V2000T	FHG1761
	FLG1925
	FH1761
	FL1925

Device	Package-Pin
XC7VX1140T	FLG1926
	FLG1928
	FLG1930
	FL1926
	FL1928

Table 2: **UltraScale™ FPGA Products Affected**

Device	Package-Pin
XCVU440	FLGA2892
	FLGB2377
XCKU085	FLVA1517
	FLVB1760
	FLVF1924
XCKU115	FLVA1517
	FLVA2104
	FLVB1760
	FLVB2104
	FLVD1517
	FLVD1924
	FLVF1924

Device	Package-Pin
XCVU125	FLVA2104
	FLVB1760
	FLVB2104
	FLVC2104
	FLVD1517
XCVU160	FLGB2104
	FLGC2104
XCVU190	FLGA2577
	FLGB2104
	FLGC2104

Key Dates and Ordering Information

Xilinx will start cross-shipping from both assembly sites starting July 1, 2017.

Qualification Data

Xilinx qualification data for Virtex-7 (28nm) and UltraScale (20nm) production parts will be available upon request. UltraScale+ (16nm) products will start shipping from both assembly locations after production release.

Response

No response is required. For additional information or questions, please contact Xilinx Technical Support.

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Revision History

The following table shows the revision history for this document.

Date	Version	Revision
4/3/2017	1.0	Initial release.

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